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FORM COVER SHEET

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ademarks:
copy thereof.

1. Name of conveying party(ies):

Kiyohito GOTOH
Hiromi ICHIOKA

10-19-00

Additional name(s) of conveying party(ies)
attached? ☐ Yes ☒ No

3. Nature of Conveyance

- ☐ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: August 23, 2000

2. Name and address of receiving party(ies):

Name: TEIJIN CHEMICALS, LTD.

Internal Address: _____

Street Address: 2-2, Uchisaiwaicho 1-chomeChiyoda-kuCity: Tokyo State: Japan ZIP: 100-0011Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

09/673624

If this document is being filed together with a new application, the execution date
of the application is: August 23, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom
correspondence concerning document
should be mailed:Name: SHERMAN & SHALLOWAY

Internal Address: _____

Street Address: _____

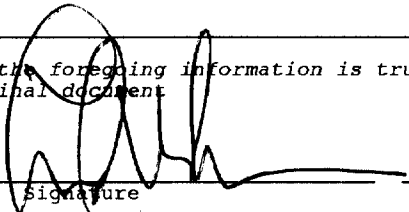
413 North Washington StreetCity: Alexandria State: VAZIP: 223146. Total number of applications and patents
involved:..... [1]7. Total fee (37 CFR 3.41).....\$40.00☒ Enclosed☐ Authorized to be charged to deposit account

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any
attached copy is a true copy of the original documentLeonard W. Sherman
Name of Person Signing
SignatureOctober 19, 2000
Date

Total number of pages including cover sheet, attachments, and document [2]

ASSIGNMENT

WHEREAS, We, Kiyohito GOTOH and Hiromi ICHIOKA

residing at Chiyoda-ku, TOKYO, JAPAN, respectively

(hereinafter referred to as Inventors), have invented certain new and useful improvements in INJECTION COMPRESSION MOLDING METHOD FOR OPTICALLY MOLDED PRODUCTS

for which an application for United States Letters Patent was signed by us on August 23, 2000 and filed in the United States on _____ and assigned Serial Number _____.

WHEREAS, Teijin Chemicals, Ltd.,
a corporation of Japan, having a place of business at 2-2, Uchisaiwaicho 1-chome, Chiyoda-ku, TOKYO 100-0011 JAPAN (hereinafter referred to as Company), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 23rd day of August, 2000.

Signed in the presence of:

Witness: <u>Tetsuo Takahashi</u>	Signed: <u>Kiyohito Gotoh</u>
Witness: _____	Signed: <u>Hiromi Ichioka</u>
Witness: _____	Signed: _____
Witness: _____	Signed: _____
Witness: _____	Signed: _____
Witness: _____	Signed: _____